Final Product Change Notification

201805007F01

Issue Date: 10-May-2018
Effective Date: 09-Jun-2018

Change Category

☐ Wafer Fab Process
☐ Wafer Fab Materials
☐ Wafer Fab Location
☐ Firmware
☐ Assembly Process
☑ Assembly Materials
☑ Assembly Location
☐ Other
☐ Product Marking
☐ Mechanical Specification
☐ Packing/Shipping/Labeling
☐ Test Location
☐ Test Process
☐ Test Equipment
☐ Design
☐ Errata
☐ Electrical spec./Test coverage

MC34708VK / VM and MC34709VK Assembly Site Transfer from SCS to ATTJ with Copper Wire

Description of Change

NXP Semiconductors announces the Assembly site transfer for the MC34708VK, MC34708VM and MC34709VK devices associated with this notification, from the current STATS ChipPAC, Singapore assembly facility to the NXP ATTJ Tianjin, China assembly facility, with Copper as the wirebond material. Full bill-of-material (BOM) change is summarized:

Current BOM STATS ChipPAC Singapore
Epoxy: Die Attach 2000B
Wire: Au 23um
Mold Compound: G760Y

New BOM NXP ATTJ Tianjin
Epoxy: Die Attach ABLEBOND 2025D
Wire: Cu 20um
Mold Compound: G760L

Assembly site transfer was successfully qualified adhering to NXP specifications.
Please see the attached qualification results for additional details.

Reason for Change

Qualification of NXP ATTJ Tianjin, China assembly site is required for customer supply assurance.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available from 10-May-2018

Production

Planned first shipment 09-Jun-2018

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: view online
Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 09-Jun-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position	Product Engineer
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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

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